

**SCOPE: CMOS 10-BIT MULTIPLYING D/A CONVERTER**

<u>Device Type</u>	<u>Generic Number</u>
01	MX7520S(x)/883B
02	MX7520T(x)/883B
03	MX7520U(x)/883B

**Case Outline(s).** The case outlines shall be designated in Mil-Std-1835 and as follows:

<u>Outline Letter</u>	<u>Mil-Std-1835</u>	<u>Case Outline</u>	<u>Package Code</u>
MAXIM			
Q	GDIP1-T16 or CDIP2-T16	16 LEAD CERDIP	J16
E	CQCCI-N20	20 LEADLESS CHIP CARRIER	L20

**Absolute Maximum Ratings**

V <sub>DD</sub> to GND .....	-0.3V, +17V
V <sub>OUT1</sub> , V <sub>OUT2</sub> , to GND .....	-0.3V, V <sub>DD</sub>
V <sub>REF</sub> to GND .....	-25V to +25V
V <sub>RFB</sub> to GND .....	-25V to +25V
Digital Input Voltage Range .....	-0.3V, V <sub>DD</sub>
Lead Temperature (soldering, 10 seconds) .....	+300°C
Storage Temperature .....	-65°C to +150°C
Continuous Power Dissipation .....	T <sub>A</sub> =+70°C
16 pin CERDIP(derate 10mW/°C above +70°C) .....	800mW
20 pin LCC(derate 9.1mW/°C above +70°C) .....	727mW
Junction Temperature T <sub>J</sub> .....	+150°C
Thermal Resistance, Junction to Case, $\theta_{JC}$	
16 pin CERDIP .....	40°C/W
20 pin LCC .....	50°C/W
Thermal Resistance, Junction to Ambient, $\theta_{JA}$ :	
16 pin CERDIP .....	20°C/W
20 pin LCC .....	110°C/W

**Recommended Operating Conditions**

Ambient Operating Range (T <sub>A</sub> ) .....	-55°C to +125°C
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Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**TABLE 1. ELECTRICAL TESTS:**

TEST	Symbol	CONDITIONS	Group A Subgroup	Device type	Limits Min	Limits Max	Units
		-55 °C <=T <sub>A</sub> <= +125°C <u>1</u> / Unless otherwise specified					
Resolution	RES	NOTE 2		All	10		Bits
Relative Accuracy	RA		1,2,3	01 02 03	-2.0 -1.0 -0.5	+2.0 -1.0 0.5	LSB
Nonlinearity Tempco	TC <sub>NL</sub>	NOTE 2		All	-2.0	+2.0	ppm/°C
Gain Tempco	TC <sub>AE</sub>	NOTE 2		All	-20	+20	ppm/°C
OUT1 Leakage Current	I <sub>OUT1</sub>	Digital inputs at V <sub>IL</sub> , VREF=+10V	1,2,3	All	-200	200	nA
OUT2 Leakage Current	I <sub>OUT2</sub>	Digital inputs at V <sub>IH</sub> , VREF=+10V	1,2,3	All	-200	200	nA
Output Current Settling Time NOTE 2		To ±0.5LSB, OUT1 load is 100Ω    13pF. Digital inputs = V <sub>IH</sub> to V <sub>IL</sub> or V <sub>IL</sub> to V <sub>IH</sub> .	4	All		0.5	μs
Feedthrough Error NOTE 3	FTE	VREF=20Vp-p at 10kHz sine wave, digital inputs at V <sub>IL</sub>	4			30	mVp-p
Reference Input Resistance	R <sub>IN</sub>		1,2,3	All	5	20	kΩ
Input High Level Voltage	V <sub>IH</sub>		1,2,3	All	2.4		V
Input Low Level Voltage	V <sub>IL</sub>		1,2,3	All		0.8	V
Input Leakage Current	I <sub>IL</sub>	V <sub>IN</sub> =0V or V <sub>DD</sub>	1,2,3	All	-1.0	1.0	μA
Output Capacitance	C <sub>OUT1</sub>	Digital Inputs at V <sub>IH</sub> Digital Inputs at V <sub>IL</sub>	4	All		120 37	pF
	C <sub>OUT2</sub>	Digital Inputs at V <sub>IH</sub> Digital Inputs at V <sub>IL</sub>				37 120	
Supply Current	I <sub>DD</sub>	Digital Inputs at V <sub>IH</sub> or V <sub>IL</sub>	1,2,3	All		2	mA

NOTE 1: V<sub>DD</sub>=+15V, V<sub>OUT1</sub>=V<sub>OUT2</sub>=0V, VREF=+10V, unless otherwise specified.

NOTE 2: Characteristics supplied for use as a typical design limit but not production tested.

NOTE 3: Feedthrough error can be reduced by connecting the lid of the ceramic SB package to ground.

**TERMINAL CONNECTIONS**

	J16, D16	20 LCC		J16, D16	20 LCC
1	OUT1	NC	11	D8	NC
2	OUT2	OUT1	12	D9	D6
3	GND	OUT2	13	D10(LSB)	D7
4	D1(MSB)	GND	14	V <sub>DD</sub>	D8
5	D2	D1(MSB)	15	VREF	D9
6	D3	NC	16	R <sub>FB</sub>	NC
7	D4	D2	17		D10(LSB)
8	D5	D3	18		V <sub>DD</sub>
9	D6	D4	19		VREF
10	D7	D5	20		R <sub>FB</sub>

	Package	ORDERING INFORMATION:
01	16 pin CERDIP	MX7520SQ/883B
01	20 pin LCC	MX7520SE/883B
02	16 pin CERDIP	MX7520TQ/883B
02	20 pin LCC	MX7520TE/883B
03	16 pin CERDIP	MX7520UQ/883B
03	20 pin LCC	MX7520UE/883B

## QUALITY ASSURANCE

Sampling and inspection procedures shall be in accordance with MIL-Prf-38535, Appendix A as specified in Mil-Std-883.

Screening shall be in accordance with Method 5004 of Mil-Std-883. Burn-in test Method 1015:

1. Test Condition, A, B, C, or D.
2. TA = +125°C minimum.
3. Interim and final electrical test requirements shall be specified in Table 2.

Quality conformance inspection shall be in accordance with Method 5005 of Mil-Std-883, including Groups A, B, C, and D inspection.

Group A inspection:

1. Tests as specified in Table 2.
2. Selected subgroups in Table 1, Method 5005 of Mil-Std-883 shall be omitted.

Group C and D inspections:

- a. End-point electrical parameters shall be specified in Table 1.
- b. Steady-state life test, Method 1005 of Mil-Std-883:
  1. Test condition A, B, C, D.
  2. TA = +125°C, minimum.
  3. Test duration, 1000 hours, except as permitted by Method 1005 of Mil-Std-883.

**TABLE 2. ELECTRICAL TEST REQUIREMENTS**

Mil-Std-883 Test Requirements	Subgroups per Method 5005, Table 1
Interim Electric Parameters Method 5004	1
Final Electrical Parameters Method 5005	1*, 2, 3, 4**
Group A Test Requirements Method 5005	1, 2, 3, 4**
Group C and D End-Point Electrical Parameters Method 5005	1

\* PDA applies to Subgroup 1 only.

\*\* Subgroup 4, Capacitance tests are performed at initial qual and upon redesign.  
Sample size will be 116 units.